

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
 Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	<b>Company Unique ID</b> 00-489-5751	<b>Unique ID Authority</b> Dun & Bradstreet	<b>Response Date*</b> Sat, Aug 09, 2014 02:31 AM
<b>Contact Name *</b> David Lancaster	<b>Title - Contact</b> Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	<b>Title - Representative</b> Product Ecology	<b>Phone - Representative *</b> 801-562-7455	<b>Email - Representative *</b> david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FDD6612A	FDD6612A	TO-252-3 (DPAK_GEM)			SUBCONTRACTOR	0.329837	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b>	<b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b>	<b>Supplier Acceptance * Accepted</b>
<p><b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p> <p>Exemption List Version EL-2011/534/EU</p> <p>7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).</p>		

#### Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name TO-252-3 (DPAK\_GEM)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	5.160	Supplier		Silicon	5.160	7440-21-3	15644
Die Attach	Other Nonferrous metals & alloys	5.157	A	Lead/Lead Compounds	Lead	4.770	7439-92-1	14462
			Supplier		Silver	0.129	7440-22-4	391
			Supplier		Tin	0.258	7440-31-5	782
Encapsulation	Thermoplastics	148.990	Supplier		Carbon Black	1.490	1333-86-4	4517
			Supplier		Epoxy Resin	11.919	29690-82-2	36137
			Supplier		Metal Hydroxide - Generic CAS#	2.980	G0007	9034
			Supplier		Phenolic resin	8.939	9003-35-4	27102
			Supplier		Silica, vitreous	123.662	60676-86-0	374918
Lead Frame	Copper & its alloys	169.000	Supplier		Copper	168.561	7440-50-8	511042
			B	Nickel (external applications only)	Nickel	0.220	7440-02-0	666
			Supplier		Tin	0.220	7440-31-5	666
Plating	Other Nonferrous metals & alloys	1.090	Supplier		Tin	1.090	7440-31-5	3305
Wire Bond	Aluminum & its alloys	0.440	Supplier		Aluminum	0.440	7429-90-5	1334